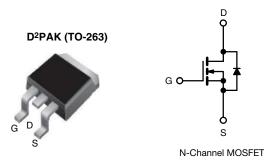




E Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.156		
Q _g max. (nC)	96			
Q _{gs} (nC)	12			
Q _{gd} (nC)	25			
Configuration	Single			



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	D ² PAK (TO-263)
Lead (Pb)-Free and Halogen-Free	SiHB22N60AE-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)								
PARAMETER			SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		V _{DS}	600	V				
Gate-Source Voltage			V _{GS}	± 30	V			
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	Γ _C = 25 °C _C = 100 °C	- I _D -	20				
	V _{GS} at 10 V	_C = 100 °C		12	А			
Pulsed Drain Current ^a			I _{DM}	49				
Linear Derating Factor				1.4	W/°C			
Single Pulse Avalanche Energy ^b			E _{AS}	204	mJ			
Maximum Power Dissipation			PD	179	W			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C				
Drain-Source Voltage Slope	T _J = 125 °C		al) (/alt	70	1//			
Reverse Diode dV/dt ^d		dV/dt	31	V/ns				
Soldering Recommendations (Peak temperature) ^c	For 10 s			300	°C			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.8 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

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SiHB22N60AE

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PARAMETER	SYMBOL	TYP.		MAX.		UNIT			
Maximum Junction-to-Ambient	R _{thJA}	-		62					
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.7				°C/W			
	•	·							
SPECIFICATIONS ($T_J = 25 \degree C$,	unless otherw	ise noted)							
PARAMETER	SYMBOL	-		ONS	MIN.	TYP.	MAX.	UNI	
Static									
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 25	50 µA	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _C	₀ = 250 μA	-	0.72	-	V/°0	
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	50 µA	2	-	4	V	
			$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}				-	-	± 1	μA	
Zene Oete Malterre Duite Original		V _{DS} =	= 600 V, V _{GS}	s = 0 V	-	-	1		
Zero Gate Voltage Drain Current	D Gate Voltage Drain Current I_{DSS} $V_{DS} = 480 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$, T _J = 125 °C	-	-	10	μA		
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D	= 11 A	-	0.156	0.180	Ω	
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D =	11 A	-	4.8	-	S	
Dynamic						•			
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz $V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$		-	1451	-	pF		
Output Capacitance	C _{oss}			-	73	-			
Reverse Transfer Capacitance	C _{rss}			-	5	-			
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	50	-			
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	258	-			
Total Gate Charge	Qg				-	48	96	nC	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	V _{GS} = 10 V I _D = 11 A, V _{DS} = 480 V		-	12	-		
Gate-Drain Charge	Q _{gd}				-	25	-		
Turn-On Delay Time	t _{d(on)}	1		-	19	38			
Rise Time	t _r		- 		-	33	66	1	
Turn-Off Delay Time	t _{d(off)}	$V_{DD} = 480 \text{ V}, \text{ I}_{D} = 11 \text{ A}, \\ V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	45	90	ns		
Fall Time	t _f			-	21	42			
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.3	0.6	1.2	Ω		
Drain-Source Body Diode Characterist									
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20	A		
Pulsed Diode Forward Current	I _{SM}			-	-	49			
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	-	1.2	V		
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 11 \text{ A},$ dl/dt = 100 A/µs, V _R = 25 V		-	319	638	ns		
Reverse Recovery Charge	Q _{rr}			-	4.9	9.8	μΟ		
Reverse Recovery Current	I _{RRM}			-	28	_	A		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

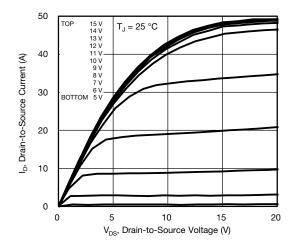


Fig. 1 - Typical Output Characteristics

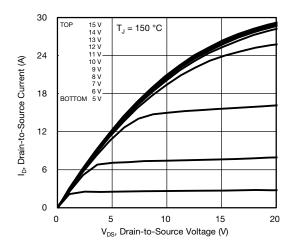
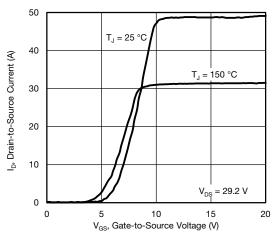


Fig. 2 - Typical Output Characteristics





S16-1715-Rev. A, 29-Aug-16

3.0 = 11 A R_{DS(on)}, Drain-to-Source On-Resistance 2.5 2.0 (Normalized) 1.5 1.0 10 \ GS 0.5 0 -20 -60 -40 20 40 60 80 100 120 140 160 0 T_J, Junction Temperature (°C)

Fig. 4 - Normalized On-Resistance vs. Temperature

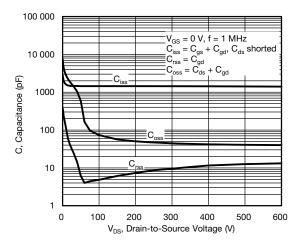


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

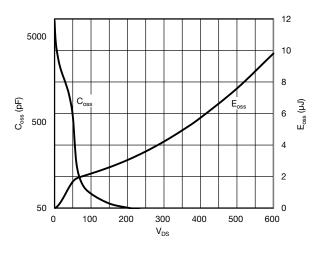


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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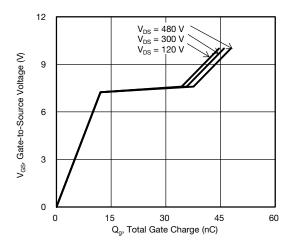


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

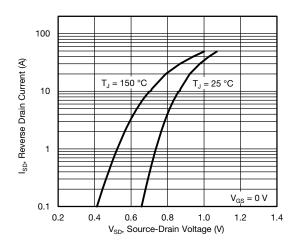


Fig. 8 - Typical Source-Drain Diode Forward Voltage

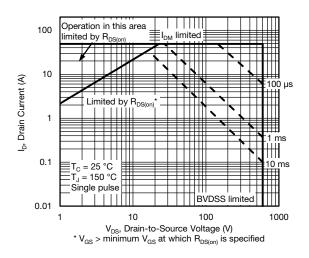


Fig. 9 - Maximum Safe Operating Area

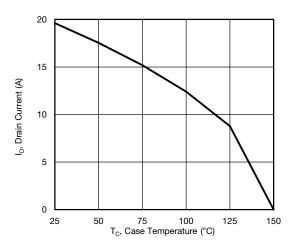


Fig. 10 - Maximum Drain Current vs. Case Temperature

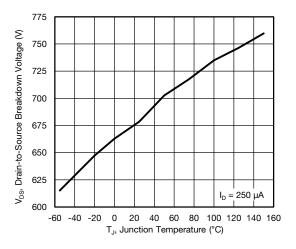


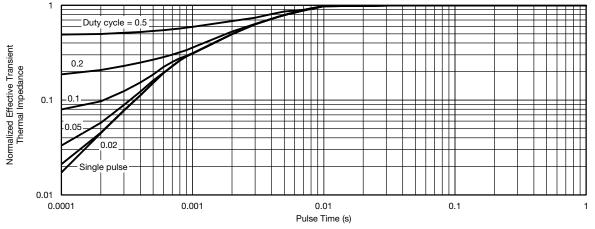
Fig. 11 - Temperature vs. Drain-to-Source Voltage

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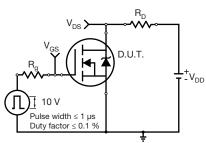


Fig. 13 - Switching Time Test Circuit

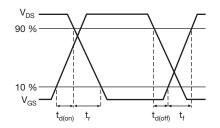


Fig. 14 - Switching Time Waveforms

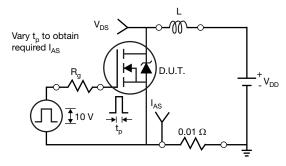


Fig. 15 - Unclamped Inductive Test Circuit

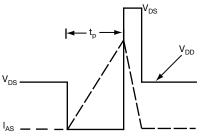


Fig. 16 - Unclamped Inductive Waveforms

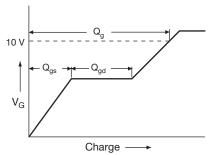


Fig. 17 - Basic Gate Charge Waveform

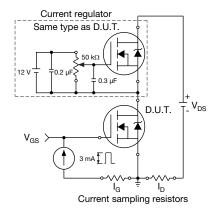


Fig. 18 - Gate Charge Test Circuit

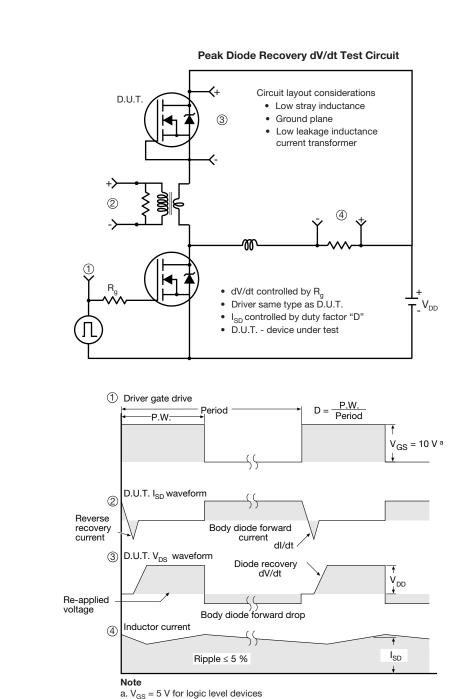


Fig. 19 - For N-Channel

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